## NB7L572

### 2.5V / 3.3V Differential 4:1 Mux Input to 1:2 LVPECL Clock/Data Fanout / Translator

## Multi-Level Inputs w/ Internal Termination

The NB7L572 is a high performance differential 4:1 Clock/Data input multiplexer and a 1:2 LVPECL Clock/Data fanout buffer. The $\mathrm{INx} / \overline{\mathrm{INx}}$ inputs includes internal $50 \Omega$ termination resistors and will accept differential LVPECL, CML, or LVDS logic levels. The NB7L572 incorporates a pair of Select pins that will choose one of four differential inputs and will produce two identical LVPECL output copies of Clock or Data operating up to 7 GHz or $10 \mathrm{~Gb} / \mathrm{s}$, respectively. As such, NB7L572 is ideal for SONET, GigE, Fiber Channel, Backplane and other Clock/Data distribution applications.

The NB7L572 INx/ $\overline{\mathrm{INx}}$ inputs, outputs and core logic are powered by a $2.5 \mathrm{~V} \pm 5 \% \mathrm{~V}$ or $3.3 \mathrm{~V} \pm 10 \%$ power supply. The two differential LVPECL outputs will swing 750 mV when externally terminated with a $50 \Omega$ resistor to $\mathrm{V}_{\mathrm{CC}}-2 \mathrm{~V}$, and are optimized for low skew and minimal jitter.

The NB7L572 is offered in a low profile $5 \times 5 \mathrm{~mm} 32$-pin QFN Pb -free package. Application notes, models, and support documentation are available at www.onsemi.com.

The NB7L572 is a member of the GigaComm ${ }^{\text {TM }}$ family of high performance clock products.

## Features

- Input Data Rate > $10.7 \mathrm{~Gb} / \mathrm{s}$ Typical
- Data Dependent Jitter < 15 ps
- Maximum Input Clock Frequency $>7 \mathrm{GHz}$ Typical
- Random Clock Jitter < 0.8 ps RMS
- Low Skew 1:2 LVPECL Outputs, < 15 ps max
- 4:1 Multi-Level Mux Inputs, Accepts LVPECL, CML LVDS
- 150 ps Typical Propagation Delay
- 45 ps Typical Rise and Fall Times
- Differential LVPECL Outputs, 750 mV Peak-to-Peak, Typical
- Operating Range: $\mathrm{V}_{\mathrm{CC}}=2.375 \mathrm{~V}$ to 3.6 V
- Internal $50 \Omega$ Input Termination Resistors
- VRefac Reference Output
- $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ Ambient Operating Temperature
- These are $\mathrm{Pb}-$ Free Devices

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ORDERING INFORMATION
See detailed ordering and shipping information in the package dimensions section on page 10 of this data sheet.


Figure 1. Pinout Configuration (Top View)

Table 1. INPUT SELECT FUNCTION TABLE

| SEL1 $^{*}$ | SEL0 $^{*}$ | Clock / Data Input Selected |
| :---: | :---: | :---: |
| 0 | 0 | INO Input Selected |
| 0 | 1 | IN1 Input Selected |
| 1 | 0 | IN2 Input Selected |
| 1 | 1 | IN3 Input Selected |

[^0]NB7L572

Table 2. PIN DESCRIPTION

| Pin | Name | 1/0 | Description |
| :---: | :---: | :---: | :---: |
| $\begin{gathered} 1,4 \\ 5,8 \\ 25,28 \\ 29,32 \end{gathered}$ |  | LVPECL, CML, LVDS Input | Non-inverted, Inverted, Differential Clock or Data Inputs. |
| $\begin{gathered} 2,6 \\ 26,30 \end{gathered}$ | $\begin{aligned} & \hline \text { VT0, VT1 } \\ & \text { VT2, VT3 } \end{aligned}$ |  | Internal $100 \Omega$ Center-tapped Termination Pin for INx / INx |
| $\begin{aligned} & 15 \\ & 18 \end{aligned}$ | $\begin{aligned} & \hline \text { SELO } \\ & \text { SEL1 } \end{aligned}$ | LVTTL/LVCMOS Input | Input Select pins, default HIGH when left open through a $28 \mathrm{k}-\Omega$ pull-up resistor. Input logic threshold is $\mathrm{V}_{\mathrm{CC}} / 2$. See Select Function, Table 1. |
| 14, 19 | NC | - | No Connect |
| $\begin{aligned} & 10,13,16 \\ & 17,20,23 \end{aligned}$ | VCC | - | Positive Supply Voltage. All $\mathrm{V}_{\mathrm{CC}}$ pins must be connected to the positive power supply for correct DC and AC operation. |
| $\begin{aligned} & 11,12 \\ & 21,22 \end{aligned}$ | $\begin{aligned} & \overline{\mathrm{QO}}, \mathrm{QO} \\ & \mathrm{Q1}, \mathrm{Q} 1 \end{aligned}$ | LVPECL Output | Inverted, Non-inverted Differential Outputs. |
| 9, 24 | GND |  | Negative Supply Voltage, connected to Ground |
| $\begin{gathered} 3 \\ 7 \\ 27 \\ 31 \end{gathered}$ | VREFACO <br> VREFAC1 <br> VREFAC2 <br> VREFAC3 | - | Output Voltage Reference for Capacitor-Coupled Inputs |
| - | EP | - | The Exposed Pad (EP) on the QFN-32 package bottom is thermally connected to the die for improved heat transfer out of package. The exposed pad must be attached to a heat-sinking conduit. The pad is electrically connected to the die, and must be electrically connected to GND. |

1. In the differential configuration when the input termination pins (VT0, VT1, V 2, $\mathrm{V} T 3$ ) are connected to a common termination voltage or left open, and if no signal is applied on $\mathrm{INx} / \mathrm{INx}$ input, then the device will be susceptible to self-oscillation.
2. All VCC, and GND pins must be externally connected to a power supply for proper operation.

Table 3. ATTRIBUTES

| Characteristic | Value |
| :--- | :---: |
| ESD ProtectionHuman Body Model <br> Machine Model | $>4 \mathrm{kV}$ <br> $>150 \mathrm{~V}$ |
| Input Pullup Resistor (ReU) | $28 \mathrm{k} \Omega$ |
| Moisture Sensitivity (Note 3) | QFN32 |

3. For additional information, see Application Note AND8003/D.

Table 4. MAXIMUM RATINGS

| Symbol | Parameter | Condition 1 | Condition 2 | Rating | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: |
| $\mathrm{V}_{\mathrm{CC}}$ | Positive Power Supply | GND $=0 \mathrm{~V}$ |  | -0.5 to +4.0 | V |
| $\mathrm{V}_{\text {IN }}$ | Positive Input Voltage | GND $=0 \mathrm{~V}$ |  | -0.5 to $\mathrm{V}_{\mathrm{CC}}+0.5$ | V |
| $\mathrm{V}_{\text {INPP }}$ | Differential Input Voltage \|IN - IN| |  |  | 1.89 | V |
| $\mathrm{I}_{\text {out }}$ | LVPECL Output Current | Continuous Surge |  | $\begin{aligned} & \hline 50 \\ & 100 \end{aligned}$ | $\begin{aligned} & \mathrm{mA} \\ & \mathrm{~mA} \end{aligned}$ |
| $\mathrm{I}_{\mathrm{N}}$ | Input Current Through RT (50 $\Omega$ Resistor) |  |  | $\pm 40$ | mA |
| $\mathrm{T}_{\text {A }}$ | Operating Temperature Range |  |  | -40 to +85 | ${ }^{\circ} \mathrm{C}$ |
| $\mathrm{T}_{\text {stg }}$ | Storage Temperature Range |  |  | -65 to +150 | ${ }^{\circ} \mathrm{C}$ |
| $\theta_{\mathrm{JA}}$ | Thermal Resistance (Junction-to-Ambient) (Note 4) | $\begin{aligned} & 0 \text { Ifpm } \\ & 500 \text { lfpm } \end{aligned}$ | $\begin{aligned} & \text { QFN-32 } \\ & \text { QFN-32 } \end{aligned}$ | $\begin{aligned} & \hline 31 \\ & 27 \end{aligned}$ | $\begin{aligned} & \hline{ }^{\circ} \mathrm{C} / \mathrm{W} \\ & { }^{\circ} \mathrm{C} / \mathrm{W} \end{aligned}$ |
| $\theta_{\text {Jc }}$ | Thermal Resistance (Junction-to-Case) (Note 4) |  | QFN-32 | 12 | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |
| $\mathrm{T}_{\text {sol }}$ | Wave Solder | $\leq 20 \mathrm{sec}$ |  | 265 | ${ }^{\circ} \mathrm{C}$ |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.
4. JEDEC standard multilayer board - 2S2P (2 signal, 2 power) with 8 filled thermal vias under exposed pad.

Table 5. DC CHARACTERISTICS POSITIVE LVPECL OUTPUT $\mathrm{V}_{\mathrm{CC}}=2.375 \mathrm{~V}$ to $3.6 \mathrm{~V}, \mathrm{GND}=0 \mathrm{~V}, \mathrm{TA}=-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ (Note 6)

| Symbol | Characteristic | Min | Typ | Max | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: |
| POWER SUPPLY |  |  |  |  |  |
| $\mathrm{V}_{\text {cc }}$ | Power Supply Voltage $\begin{gathered} \\ V_{\mathrm{CC}}=2.5 \mathrm{~V} \\ \mathrm{~V}_{\mathrm{CC}}=3.3 \mathrm{~V}\end{gathered}$ | $\begin{gathered} 2.375 \\ 3.0 \end{gathered}$ | $\begin{aligned} & 2.5 \\ & 3.3 \end{aligned}$ | $\begin{gathered} 2.625 \\ 3.6 \end{gathered}$ | V |
| $\mathrm{I}_{\mathrm{CC}}$ | Power Supply Current for $\mathrm{V}_{\mathrm{CC}}$ (Inputs and Outputs Open) |  | 90 | 110 | mA |

LVPECL OUTPUTS

| $\mathrm{V}_{\mathrm{OH}}$ | Output HIGH Voltage (Note 6) | $\begin{aligned} & \mathrm{V}_{\mathrm{CC}}=2.5 \mathrm{~V} \\ & \mathrm{~V}_{\mathrm{CC}}=3.3 \mathrm{~V} \end{aligned}$ | $\begin{gathered} \hline \mathrm{V}_{\mathrm{CC}}-1145 \\ 1355 \\ 2155 \end{gathered}$ | $\begin{gathered} \mathrm{V}_{\mathrm{CC}}-900 \\ 1600 \\ 2400 \end{gathered}$ | $\begin{gathered} \hline \mathrm{V}_{\mathrm{CC}}-825 \\ 1675 \\ 2475 \end{gathered}$ | mV |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| $\mathrm{V}_{\text {OL }}$ | Output LOW Voltage (Note 6) | $\begin{aligned} & \mathrm{V}_{\mathrm{CC}}=2.5 \mathrm{~V} \\ & \mathrm{~V}_{\mathrm{CC}}=3.3 \mathrm{~V} \end{aligned}$ | $\begin{gathered} \hline \mathrm{V}_{\mathrm{CC}}-2000 \\ 500 \\ 1300 \end{gathered}$ | $\begin{gathered} \mathrm{V}_{\mathrm{CC}}-1700 \\ 800 \\ 1600 \end{gathered}$ | $\begin{gathered} \mathrm{V}_{\mathrm{CC}}-1500 \\ 1000 \\ 1800 \end{gathered}$ | mV |

DIFFERENTIAL CLOCK INPUTS DRIVEN SINGLE-ENDED (Figures 4 \& 6) (Note 7)

| $\mathrm{V}_{\mathrm{IH}}$ | Single-Ended Input HIGH Voltage | $\mathrm{V}_{\mathrm{th}}+100$ |  | $\mathrm{~V}_{\mathrm{CC}}$ | mV |
| :--- | :--- | :---: | :---: | :---: | :---: |
| $\mathrm{V}_{\mathrm{IL}}$ | Single-Ended Input LOW Voltage | GND |  | $\mathrm{V}_{\mathrm{th}}-100$ | mV |
| $\mathrm{V}_{\mathrm{th}}$ | Input Threshold Reference Voltage Range (Note 8) | 1100 |  | $\mathrm{~V}_{\mathrm{CC}}-100$ | mV |
| $\mathrm{V}_{\text {ISE }}$ | Single-Ended Input Voltage $\left(\mathrm{V}_{\mathrm{IH}}-\mathrm{V}_{\mathrm{IL}}\right)$ | 200 |  | 2400 | mV |

VREFAC

| $\mathrm{V}_{\text {REF-AC }}$ | Output Reference Voltage (100 $\mu \mathrm{A}$ Load) | $\mathrm{V}_{\mathrm{CC}}-1500$ | $\mathrm{~V}_{\mathrm{CC}}-1200$ | $\mathrm{~V}_{\mathrm{CC}}-1000$ | mV |
| :--- | :--- | :--- | :--- | :--- | :--- |

DIFFERENTIAL INPUTS DRIVEN DIFFERENTIALLY (Figures 5 \& 7) (Note 9)

| $\mathrm{V}_{\text {IHD }}$ | Differential Input HIGH Voltage (IN, IN) | 1200 |  | $\mathrm{~V}_{\mathrm{CC}}$ | mV |
| :--- | :--- | :---: | :---: | :---: | :---: |
| $\mathrm{V}_{\text {ILD }}$ | Differential Input LOW Voltage (IN, IN) | 0 |  | $\mathrm{~V}_{\text {IHD }}-100$ | mV |
| $\mathrm{V}_{\text {ID }}$ | Differential Input Voltage (IN, IN) (V $\left.\mathrm{V}_{\text {IHD }}-\mathrm{V}_{\text {ILD }}\right)$ | 100 |  | 1200 | mV |
| $\mathrm{V}_{\mathrm{CMR}}$ | Input Common Mode Range (Differential Configuration, Note 10) <br> (Figure 8) | 800 |  | $\mathrm{~V}_{\mathrm{CC}}-50$ | mV |
| $\mathrm{I}_{\mathrm{IH}}$ | Input HIGH Current IN/IN (VT IN/VT IN Open) | -150 |  | 150 | $\mu \mathrm{~A}$ |
| $\mathrm{I}_{\mathrm{IL}}$ | Input LOW Current IN/IN (VT IN/VT IN Open) | -150 |  | 150 | $\mu \mathrm{~A}$ |

CONTROL INPUT (SELx Pin)

| $\mathrm{V}_{\mathrm{IH}}$ | Input HIGH Voltage for Control Pin | 2.0 |  | $\mathrm{~V}_{\mathrm{CC}}$ | V |
| :--- | :--- | :---: | :---: | :---: | :---: |
| $\mathrm{V}_{\mathrm{IL}}$ | Input LOW Voltage for Control Pin | GND |  | 0.8 | V |
| $\mathrm{I}_{\mathrm{IH}}$ | Input HIGH Current |  |  | 40 | $\mu \mathrm{~A}$ |
| $\mathrm{I}_{\mathrm{IL}}$ | Input LOW Current | -215 |  | 0 | $\mu \mathrm{~A}$ |

TERMINATION RESISTORS

| $\mathrm{R}_{\text {TIN }}$ | Internal Input Termination Resistor (Measured from INx to VTx) | 45 | 50 | 55 | $\Omega$ |
| :--- | :--- | :--- | :--- | :--- | :--- |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm . Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.
5. Input and Output parameters vary $1: 1$ with $\mathrm{V}_{\mathrm{CC}}$.
6. LVPECL outputs loaded with $50 \Omega$ to $\mathrm{V}_{\mathrm{CC}}-2 \mathrm{~V}$ for proper operation.
7. Vth, $\mathrm{V}_{\mathrm{IH}}, \mathrm{V}_{\text {IL }}$, and $\mathrm{V}_{\text {ISE }}$ parameters must be complied with simultaneously.
8. Vth is applied to the complementary input when operating in single-ended mode.
9. $\mathrm{V}_{I H D}, \mathrm{~V}_{I L D}, \mathrm{~V}_{I D}$ and $\mathrm{V}_{\mathrm{CMR}}$ parameters must be complied with simultaneously.
10. $\mathrm{V}_{\text {CMR }}$ min varies $1: 1$ with $\mathrm{GND}, \mathrm{V}_{\mathrm{CMR}}$ max varies $1: 1$ with $\mathrm{V}_{\mathrm{CC}}$. The $\mathrm{V}_{\mathrm{CMR}}$ range is referenced to the most positive side of the differential input signal.

Table 6. AC CHARACTERISTICS $\mathrm{V}_{\mathrm{CC}}=2.375 \mathrm{~V}$ to 3.6 V , $\mathrm{GND}=0 \mathrm{~V}, \mathrm{TA}=-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ (Note 11)

| Symbol | Characteristic |  | Min | Typ | Max | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| $\mathrm{f}_{\text {MAX }}$ | Maximum Input Clock Frequency $\mathrm{V}_{\text {OUT }} \geq 400 \mathrm{mV}$ |  | 7 | 8 |  | GHz |
| fiatamax | Maximum Operating Data Rate NRZ, (PRBS23) |  | 10 | 11 |  | Gbps |
| V OUTPP | Output Voltage Amplitude (@ $\mathrm{V}_{\text {INPPmin }}$ ) (Figure 2 \& 9) (Note 12) |  | $\begin{aligned} & 550 \\ & 400 \end{aligned}$ | $\begin{aligned} & 750 \\ & 500 \end{aligned}$ |  | mV |
| $\begin{aligned} & \text { tpLH, } \\ & \text { tPHL } \end{aligned}$ | Propagation Delay to Differential Outputs Measured at Differential Cross-Point | @ $1 \mathrm{GHz} \operatorname{INx} / \mathrm{INx}$ to $\mathrm{Qx} / \mathrm{Qx}$ (Figure 9) <br> @ 50 MHz SELx to Qx (Figure 10) | $\begin{aligned} & 125 \\ & 300 \end{aligned}$ | 150 | $\begin{gathered} 175 \\ 1000 \end{gathered}$ | ps |
| tpD Tempco | Differential Propagation Delay Temperature Coefficient |  |  | 115 |  | fs $/{ }^{\circ} \mathrm{C}$ |
| $\mathrm{t}_{\text {skew }}$ | $\begin{array}{\|l} \hline \text { Output - Output skew (within device) (Note 13) } \\ \text { Device - Device skew (tpd max - tpd min) } \end{array}$ |  |  | 0 | $\begin{aligned} & \hline 10 \\ & 50 \end{aligned}$ | ps |
| $t_{\text {DC }}$ | Output Clock Duty Cycle (Reference Duty Cycle = 50\%) |  | 45 | 50 | 55 | \% |
| $\mathrm{t}_{\text {IITTER }}$ | Additive Random Clock Jitter, RJ(RMS) (Note 14) $\mathrm{f}_{\text {in }} \leq 7.0 \mathrm{GHz}$ <br> Data Dependent Jitter, DDJ (Note 15) $\mathrm{f}_{\mathrm{in}} \leq 10 \mathrm{Gbps}$ |  |  | $\begin{gathered} 0.5 \\ 6 \end{gathered}$ | $\begin{aligned} & 0.8 \\ & 15 \end{aligned}$ | ps rms ps pk-pk |
| $\mathrm{V}_{\text {INPP }}$ | Input Voltage Swing (Differential Configuration) (Note 16) |  | 100 |  | 1200 | mV |
| $\mathrm{t}_{\mathrm{r},} \mathrm{t}_{\mathrm{f}}$ | Output Rise/Fall Times @ 1 GHz ; (20\%-80\%), $\mathrm{V}_{\mathrm{IN}}=800 \mathrm{mV} \mathrm{Q}, \overline{\mathrm{Q}}$ |  | 25 | 45 | 65 | ps |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm . Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.
11. Measured using a $100 \mathrm{mVpk}-\mathrm{pk}$ source, $50 \%$ duty cycle clock source. All output loading with external $50 \Omega$ to $\mathrm{V}_{\mathrm{CC}}-2 \mathrm{~V}$. Input edge rates $40 \mathrm{ps}(20 \%-80 \%)$.
12. Output voltage swing is a single-ended measurement operating in differential mode.
13. Skew is measured between outputs under identical transitions and conditions. Duty cycle skew is defined only for differential operation when the delays are measured from cross-point of the inputs to the cross-point of the outputs.
14. Additive RMS jitter with $50 \%$ duty cycle clock signal.
15. Additive Peak-to-Peak data dependent jitter with input NRZ data at K28.5.
16. Input voltage swing is a single-ended measurement operating in differential mode.


Figure 2. CLOCK Output Voltage Amplitude (V ${ }_{\text {OUTPP }}$ ) / RMS Jitter vs. Input Frequency ( $\mathrm{f}_{\text {in }}$ ) at Ambient Temperature (typical)


Figure 3. Input Structure


Figure 4. Differential Input Driven Single-Ended


Figure 6. $\mathbf{V}_{\text {th }}$ Diagram


Figure 8. $\mathrm{V}_{\mathrm{CMR}}$ Diagram


Figure 5. Differential Inputs Driven Differentially


Figure 7. Differential Inputs Driven Differentially


Figure 9. AC Reference Measurement


Figure 10. SELx to Qx Timing Diagram


Figure 11. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8020/D - Termination of ECL Logic Devices.)



Figure 14. Standard $50 \Omega$ Load CML Interface


Figure 15. Capacitor-Coupled Differential Interface (VT Connected to V REFAC)

* $\mathrm{V}_{\text {REFAC }}$ bypassed to ground with a $0.01 \mu \mathrm{~F}$ capacitor


Figure 16. Capacitor-Coupled Single-Ended Interface
(VT Connected to External $\mathrm{V}_{\text {REFAC }}$ )

ORDERING INFORMATION

| Device | Package | Shipping $^{\dagger}$ |
| :--- | :---: | :---: |
| NB7L572MNG | QFN32 <br> (Pb-Free) | 79 Units / Rail |
| NB7L572MNR4G | QFN32 <br> (Pb-Free) | $1000 /$ Tape \& Reel |

$\dagger$ For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

QFN32 5x5, 0.5P
CASE 488AM ISSUE A

DATE 23 OCT 2013
SCALE 2:1


1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M, 1994
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED

TERMINAL AND IS MEASURED BETWEEN
0.15 AND 0.30MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

| DIM | MILLIMETERS |  |
| :---: | :---: | :---: |
|  | MIN | MAX |
| A | 0.80 | 1.00 |
| A1 | --- | 0.05 |
| A3 | 0.20 REF |  |
| b | 0.18 | 0.30 |
| D | 5.00 BSC |  |
| D2 | 2.95 | 3.25 |
| E | 5.00 BSC |  |
| E2 | 2.95 | 3.25 |
| e | 0.50 BSC |  |
| K | 0.20 | --- |
| L | 0.30 | 0.50 |
| L1 | --- | 0.15 |

GENERIC
MARKING DIAGRAM*

1 | 0 |
| :---: |
| XXXXXXXX |
| XXXXXXXX |
| AWLYYWW: |
| $\cdot$ |

XXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week

- = Pb-Free Package

RECOMMENDED SOLDERING FOOTPRINT*

*For additional information on our $\mathrm{Pb}-F r e e$ strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.
(Note: Microdot may be in either loca-
*+ifn) information is generic. Please refer to device data sheet for actual part marking.
Pb-Free indicator, " G " or microdot " $\quad$ ", may or may not be present.

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[^0]:    *Defaults HIGH when left open.

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